

## ABSTRACT OF THE DISCLOSURE

A semiconductor device capable of reducing a fabrication period as well as a fabrication cost when timing control for signal transmission is necessary is obtained. This semiconductor device comprises a first semiconductor chip consisting of at least either a circuit against static damage or a passive component. When a plurality of semiconductor chips installed on a support substrate are connected with each other through the first semiconductor chip, timing control for signal transmission is enabled by simply modifying the first semiconductor chip. In this case, the first semiconductor chip having a relatively simple structure can be modified in a shorter time at a lower cost as compared with a case of re-forming a semiconductor chip having an individual function. Thus, the modification period as well as the modification cost can be reduced when timing control for signal transmission is necessary.